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EVG, Korea National Nanofab Center Sign MoU on Nanotech, IoT Sensors – October 26, 2022

EVG, Korea National Nanofab Center Sign MoU on Nanotech, IoT Sensors

The Korea National NanoFab Center (NNFC) and EV Group had signed a memorandum of understanding (MOU) on cooperation in the fields of nanotechnology and Internet of Things (IoT) sensors. The two parties will bring their respective expertise to advance nanotechnology and IoT. NNFC is a nano-technology R&D infrastructure for academia, research institutes and the industry. Meanwhile, EVG is a leading provider of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets.

Dr. Kim HeeYeoun, NNFC R&D Director and Dr. Wellnew Thallner, EVG's Executive Operations and Finacial Director (center) during the signing of MoU.

EVG has a long history of partnership with NNFC. They develop and commercialize new technologies for a variety of applications and industries through continued technical exchanges, exhibitions, and academic research. NNFC is the largest public service organization in the nano-process and post-process fields in Korea.

With the new MOU, both parties agreed to revitalize domestic and foreign-related fields through their activities. They will share equipment and process roadmaps and further expand their cooperation in nanotechnology and IoT sensors.

Earlier this year, EVG received a Supplier Excellence Award from the NNFC. The prestigious award was presented during a ceremony held by the NNFC on January 26 to celebrate the cooperation and creation of a culture of shared growth between the NNFC and its customers and partners. EVG is one of only two companies to receive this year's Supplier Excellence Award from the NNFC. The company was recognized for its long-term product service and support, close cooperation and consultation on

optimizing product and facility operational efficiency. Its contribution on technical consultation on new wafer bonding and related processes to support new research and device applications was also acknowledged.

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